MA2J1150G

Silicon epitaxial planar type

For small power current rectification

■ Features

- S-mini type package, allowing high-density mounting
- High reverse voltage V_R

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	200	V
Maximum peak reverse voltage	V_{RM}	200	V
Output current	I _O	200	mA
Repetitive peak forward current	I_{FRM}	600	μΑ
Non-repetitive peak forward surge current *	I _{FSM}	1	A
Junction temperature	T _j	150	°C
Storage temperature	T_{stg}	-55 to +150	°C

Note) *: t = 1 s

■ Package

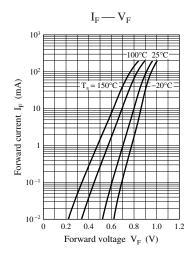
- Code
- SMini2-F3
- Pin Name 1: Anode
- 2: Cathode
- Marking Symbol: 1F

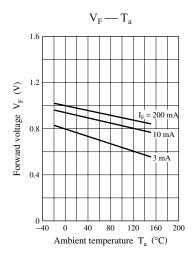
■ Electrical Characteristics $T_a = 25$ °C ± 3 °C

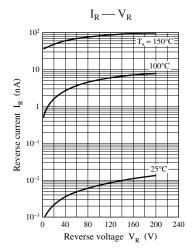
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	V_{F}	$I_F = 200 \text{ mA}$			1.2	V
Reverse current	I_R	$V_R = 200 \text{ V}$			200	nA
Terminal capacitance	C _t	$V_R = 0 V, f = 1 MHz$		4.5		pF

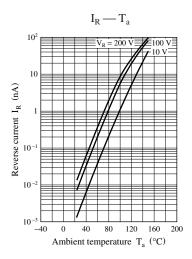
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

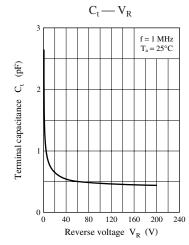
2. Absolute frequency of input and output is 3 MHz.

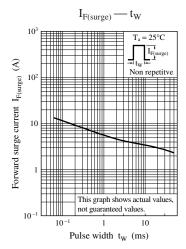






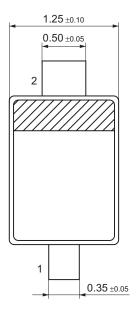


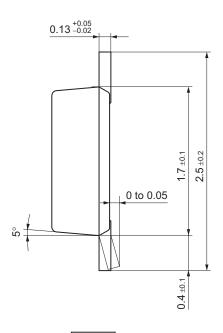


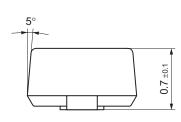


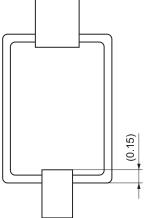
2 SKF00094AED

SMini2-F3 Unit: mm









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